

Item	Qty	Reference	Type	Part Name	MFR	Value	Package	Description
1	2	C5 C15	Ceramic Capacitor	Std	std	0.1uF	603	Capacitor, Ceramic, 10%
2	1	C10	Ceramic Capcitor	Std	Std	100pF, Y1	Lead type	Capacitor, Ceramic, Chip, 5%
3	1	C4	Ceramic Capacitor	C3216X7R1E106K	TDK	10uF,25V	1206	Capacitor, Ceramic, Chip, 10%
4	1	C12	Ceramic Capacitor	Std	std	1nF	603	Capacitor, Ceramic, 10%
5	1	C3	Ceramic Capcitor	GRM31A7U2J331JW31D	Murata	330pF,630V	1206	Capacitor, Ceramic, Chip, 5%
6	1	D6	Switching diode	BAS20HT1G	ON	0.2A,200V	SOD323	Switching diode, SMD
7	1	D7	Schotty rectifier	PDS1040	Diodes	10A,40V	POWERDI	Schotty Rectifier, 10A, 40V
8	5	D1-5	Standard rectifier	DFLR1600	Diodes	1A,600V	SOD123FL	Standard Rectifier, 1A, 600V
9	1	L3	Ferrite bead	HF70ACC322513	TDK		1210	52ohm@100MHz
10	1	L1	Common filter	LC6-137	Jepuls	600uH	T6x3x3	or Kechang TCH10 core,T6x3x3, 0.2mm wire, 10T
11	1	F1	Fuse	std	std	2A/300Vac (T)	Leaded type	Square fuse, 2A/300V, size: 8.5mm(L)X4(W)mmX8mm(H)
12	1	Q2	NMOSFET	SW6N70	SAMWIN	6A, 700V	DPAK	NMOS, 6A, 700V, DPAK
13	1	NTC1	NTC	NCP18WF104F12RB	MuRata	100K	603	NTC, Murata,0603
14	1	L2	Axial leaded fixed inductor	7447462221	Würth	220uH	Lead type	Axial leaded fixed inductor
15	1	T1	Transformer	EFD20	WE-midcon/ Jepuls		TH type	Jepuls PN: BCK2001-190
16	1	R25	Resistor	Std	Std	0	805	Resistor, Chip, 1/5W, 1%
17	1	R9	Resistor	Std	Std	1.5M	603	Resistor, Chip, 1/8W, 1%
18	1	R3	Resistor	Std	Std	2.7k	603	Resistor, Chip, 1/8W, 1%
19	1	R6	Resistor	Std	Std	22	603	Resistor, Chip, 1/8W, 1%
20	1	R17	Resistor	Std	Std	240k	603	Resistor, Chip, 1/8W, 1%
21	1	R8	Resistor	Std	Std	39k	603	Resistor, Chip, 1/8W, 1%
22	1	R7	Resistor	Std	Std	68K	805	Resistor, Chip, 1/5W, 1%
23	1	R18	Resistor	Std	Std	68k	603	Resistor, Chip, 1/8W, 1%
24	1	R4	Resistor	Std	Std	1.1	1206	Resistor, Chip, 1/4W, 1%
25	1	R19	Resistor	Std	Std	10	603	Resistor, Chip, 1/8W, 1%
26	2	R2 R16	Resistor	Std	Std	150	1206	Resistor, Chip, 1/4W, 1%
27	1	R5	Resistor	Std	Std	2	1206	Resistor, Chip, 1/4W, 1%
28	1	R12	Resistor	Std	Std	20	805	Resistor, Chip, 1/5W, 1%
29	1	R1	Resistor	Std	Std	330k	1206	Resistor, Chip, 1/4W, 1%

30	1	R15	Resistor	Std	Std	100k	603	Resistor, Chip, 1/8W, 1%
31	1	R14	Resistor	Std	Std	330k	603	Resistor, Chip, 1/8W, 1%
32	1	R13	Resistor	Std	Std	NA	805	Resistor, Chip, 1/5W, 1%
33	2	C1-2	Electrolytic capacitor	KSH126M400S1T5H1 CK	TEAPO	12uF,400V	10mm(die.)x12. 5mm(hight)	size,10mmx12.5mm
34	2	C13-14	Electrolytic solid capacitor	PCG827M6R3S1ANE 09K	TEAPO	820uF,6.3V	6.3mm(die.)x9 mm(hight)	size, 6.3mmx9mm
35	1	Q1	MOSFET	CSD18502Q5B	TI		QFN5X6mm	MOSFET, NChan, 40V, 100A
36	1	U2	PSR controller	UCC28713	TI		SO-8	PSR controller
37	1	U1	Controller	UCC24610D	TI		SO-8	IC, SECONDARY-SIDE SYNCHRONOUS RECTIFIER CONTROLLER FOR 5V SYSTEMS

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